TAS5622ADDV/TAS5624ADDV EVALUATION BOARD (RevB)





TAS5622ADDV/TAS5624ADDV **EVALUATION BOARD** (RevB) LOUT+ C20 C21 C22 LEFT 0.01ufd/100V 0805 X7R Output 0.68ufd/250V MKP4-15 1000pfd/100V 1206 COG ()LOUT+ **R8** 0603 -OLOUT-GND Black LOUT-C23 C24 C25 0.68ufd/250V MKP4-15 1000pfd/100V 1206 COG 0.01ufd/100V 0805 X7R **R9** 3.3 0603 GND GND GND -**OR**+ ROUT+ C26 C27 C28 RIGHT Output 0.01ufd/100V 0805 X7R 0.68ufd/250V MKP4-15 1000pfd/100V 1206 COG OROUT+ GND R10 **3.3** Red OROUT-GND Black ROUT-C29 C30 C31 0.68ufd/250V MKP4-15 1000pfd/100V 1206 COG 0.01ufd/100V 0805 X7R GND GND 2 R11 **3.3** GND **CR2** 30BQ060 60V/580mV@3A SMC CR3 30BQ060 60V/580mV@3A CR4 30BQ060 60V/580mV@3A SMC SMC GND GND GND

	SCH REV B
	PCB REV B
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REVISION HISTORY	REV	ISION		FORY
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REVISION HISTORY			
REVISION	DESCRIPTION	DATE	APPROVAL
А	INITIAL RELEASE	MARCH 7, 2012	SC
В	 CHANGE U2 FROM TAS5548DGG TO TAS5558DCA. DELETED ET2. SHORTED ACROSS AND DELETED R51. CHANGED HEATSINK TO MODEL 519. 	MAY 6, 2013	BW



PAGE INFO:	REVISION HISTORY	DATE	MAY 6, 2013
DESIGN LEAD	BRIAN WANG	FILENAME	TAS5622A-TAS



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	PCB REV	В
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